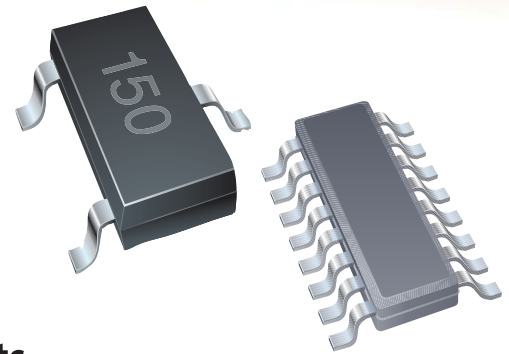




Product Change Notification

CHIP DIODES

Bourns Manufacturers Representatives
Corporate Distributor Product Managers
Americas Sales Team
Asia Sales Team
Europe Sales Team



November, 2009

Bourns® Diode Products **Addition of Second Wafer Fabrication Location** **and Change to Sumitomo's Green Mold Compound**

Bourns is adding a second wafer fabrication location, in the UK, for the diode part numbers below for continued secure supply chain management and delivery support to our customers.

| Bourns P/N | Bourns P/N | Bourns P/N |
|------------------------------|------------------------------|-------------------------------|
| CDNBS16-T03 | CDNBS16-T12C | CDSOT23-T03LC |
| CDNBS16-T03C | CDNBS16-T15 | CDSOT23-T05LC |
| CDNBS16-T05 | CDNBS16-T15C | CDSOT23-T08LC |
| CDNBS16-T05C | CDNBS16-T24 | CDSOT23-T12LC |
| CDNBS16-T08 | CDNBS16-T24C | CDSOT23-T15LC |
| CDNBS16-T08C | CDNBS16-T36 | CDSOT23-T24LC |
| CDNBS16-T12 | CDNBS16-T36C | CDSOT23-T36LC |

Bourns will change to the Green Sumitomo G600 mold compound in the above packages.

Some product using the new "Green" mold compound can be available immediately if requested by customers.

Reliability data, SGS and MDS reports on the units' package assembly incorporating the above changes will be available on January 1, 2010.

Bourns is issuing 90 days notice that mass production with the above changes will begin February 10, 2010.